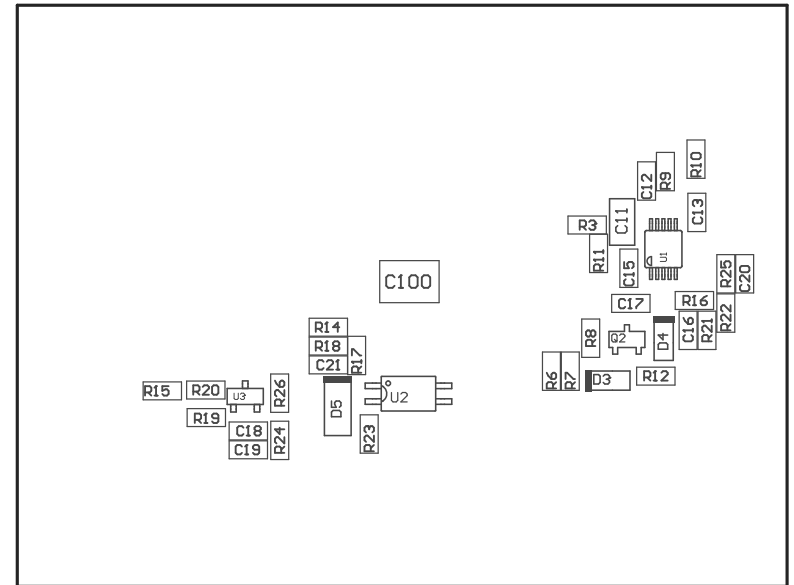


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP30252	REV: A	SVN REV: Not In VersionControl
	TID #:		
PLOT NAME = Top Assembly Drawing	GENERATED : 8/21/2017 14:50:33	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP30252	REV: A	SVN REV: Not In VersionControl
	TID #:		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 8/21/2017 14:50:34		TEXAS INSTRUMENTS

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